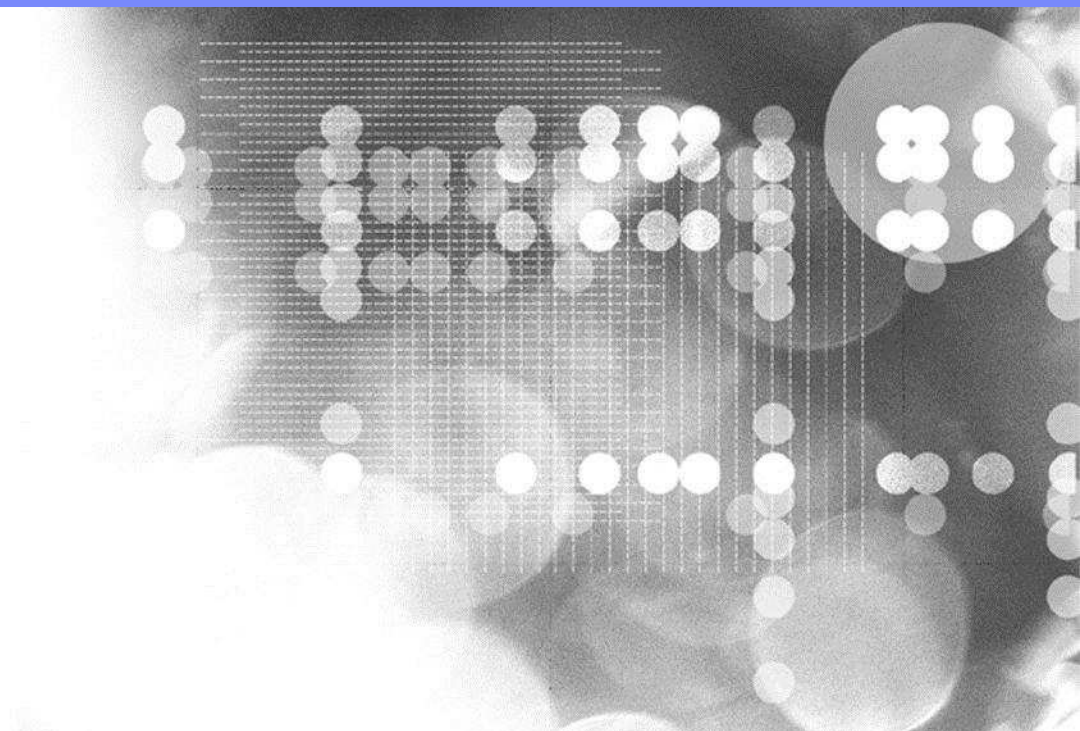




POWER7+™

IBM

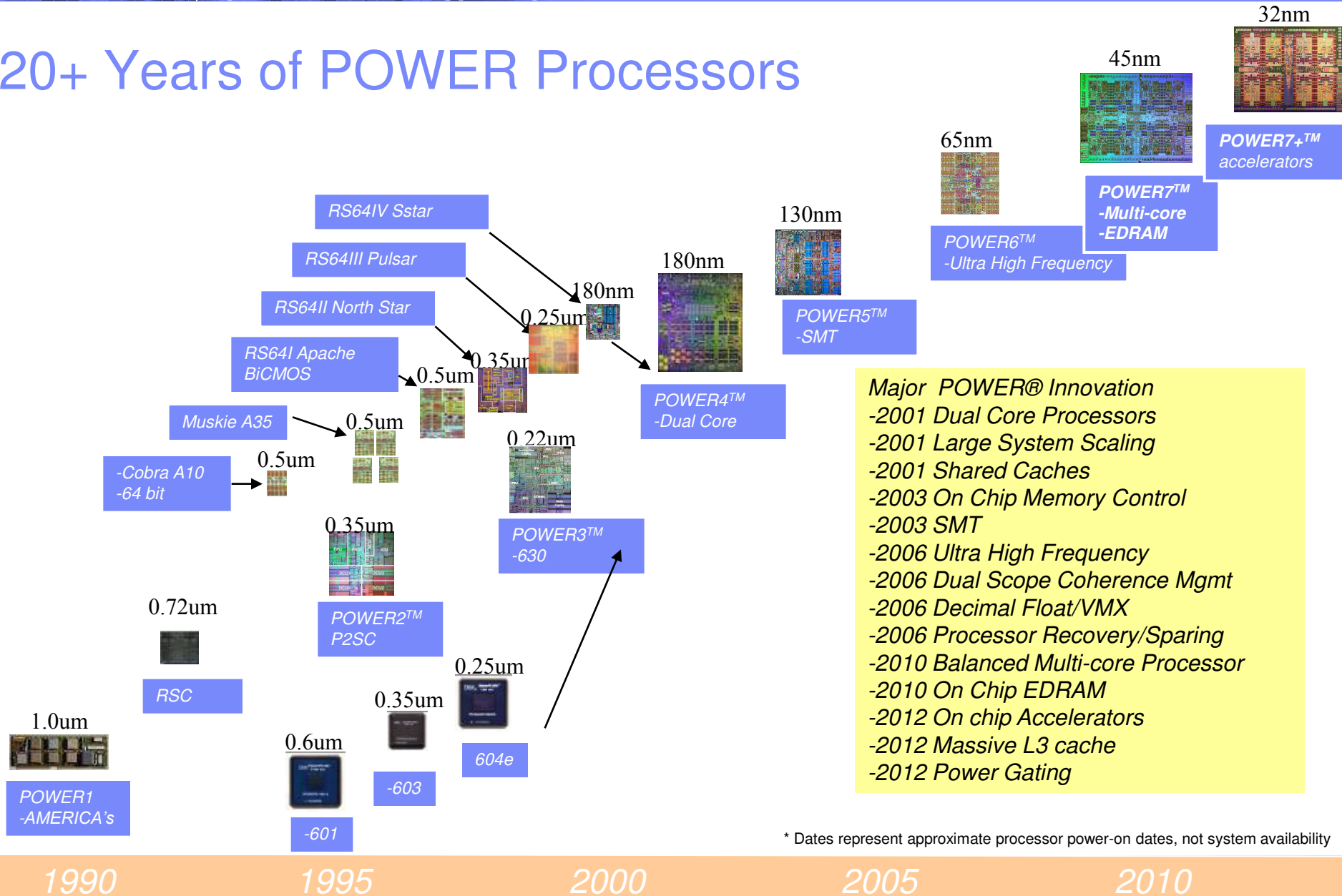


# Outline

- POWER Processor History
- Design Overview
- Performance Benchmarks
- Key Features
  - Scale-up / Scale-out
  - The new accelerators
  - Advanced energy management
- Summary

\* Statements regarding Power7+™ features do not imply that IBM will introduce a system with this capability

# 20+ Years of POWER Processors



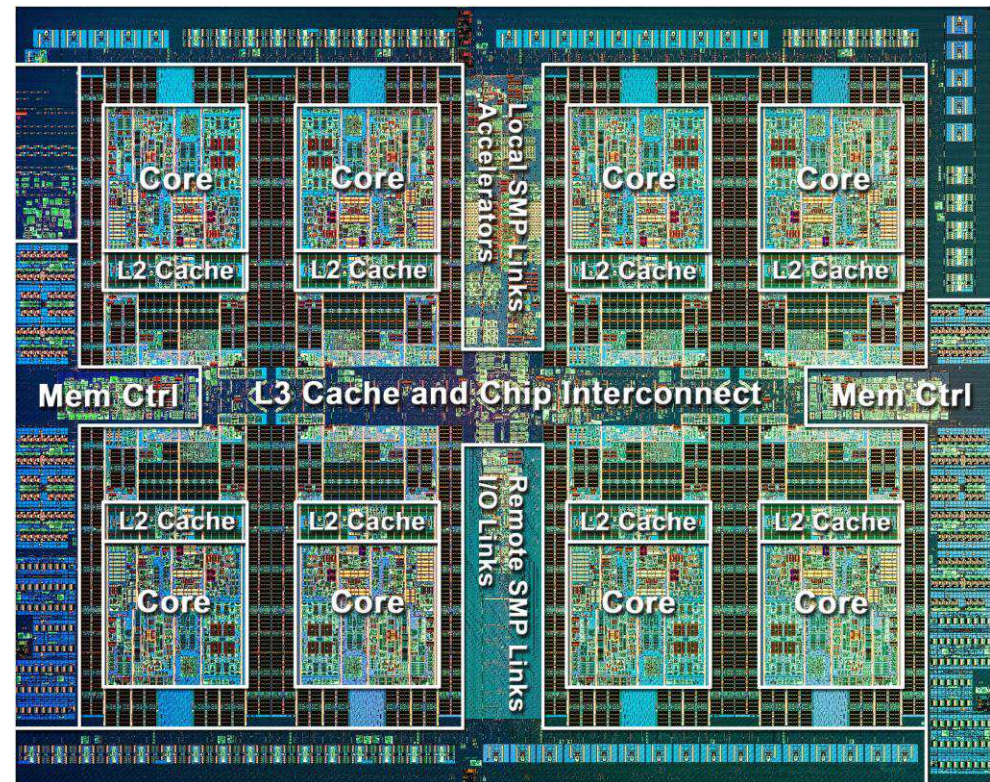
- Major POWER® Innovation**
- 2001 Dual Core Processors
  - 2001 Large System Scaling
  - 2001 Shared Caches
  - 2003 On Chip Memory Control
  - 2003 SMT
  - 2006 Ultra High Frequency
  - 2006 Dual Scope Coherence Mgmt
  - 2006 Decimal Float/VMX
  - 2006 Processor Recovery/Sparing
  - 2010 Balanced Multi-core Processor
  - 2010 On Chip EDRAM
  - 2012 On chip Accelerators
  - 2012 Massive L3 cache
  - 2012 Power Gating

\* Dates represent approximate processor power-on dates, not system availability



# POWER7+ Processor Chip

- Area: 567mm<sup>2</sup>
- Eight processor cores
  - 12 execution units per core
  - 4 Way SMT per core
  - 32 Threads per chip
  - 256KB L2 per core
- Scalability up to 32 Sockets
  - 360GB/s SMP bandwidth/chip
  - 20,000 coherent operations in flight
- Technology: 32nm lithography, Cu, SOI, eDRAM, 13 metal levels
- 2.1B transistors
  - Equivalent function of 5.4B
- 80MB on chip eDRAM shared L3
- Accelerators
- Enhanced Power management
- Binary Compatibility with POWER6/7



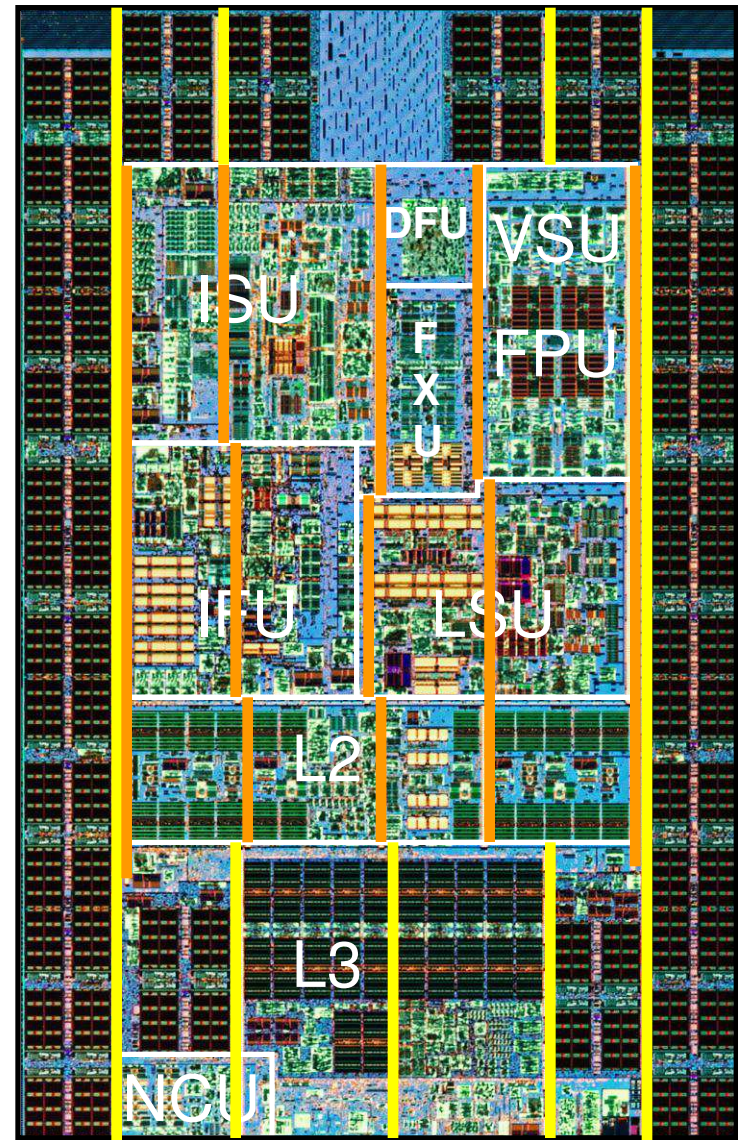


## An Improved Core

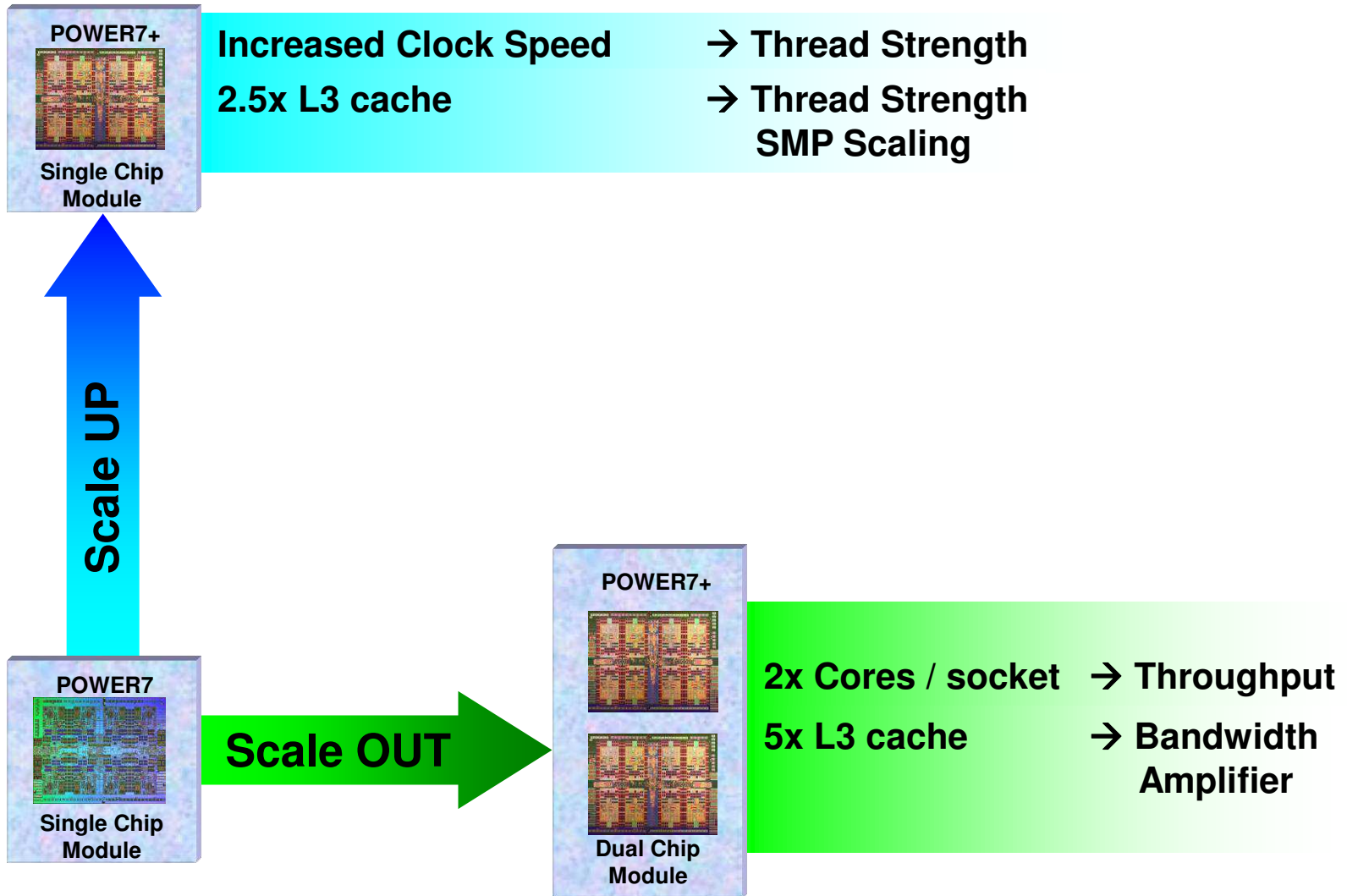
- Up to 25% frequency gain due to mapping into 32nm technology and power management improvements.
- Increase of L3 memory capacity by 2.5x
- Doubled single precision floating-point performance
- Added Power Gating regions for Core/L2 & L3 regions

Core/L2 Power-Gating 

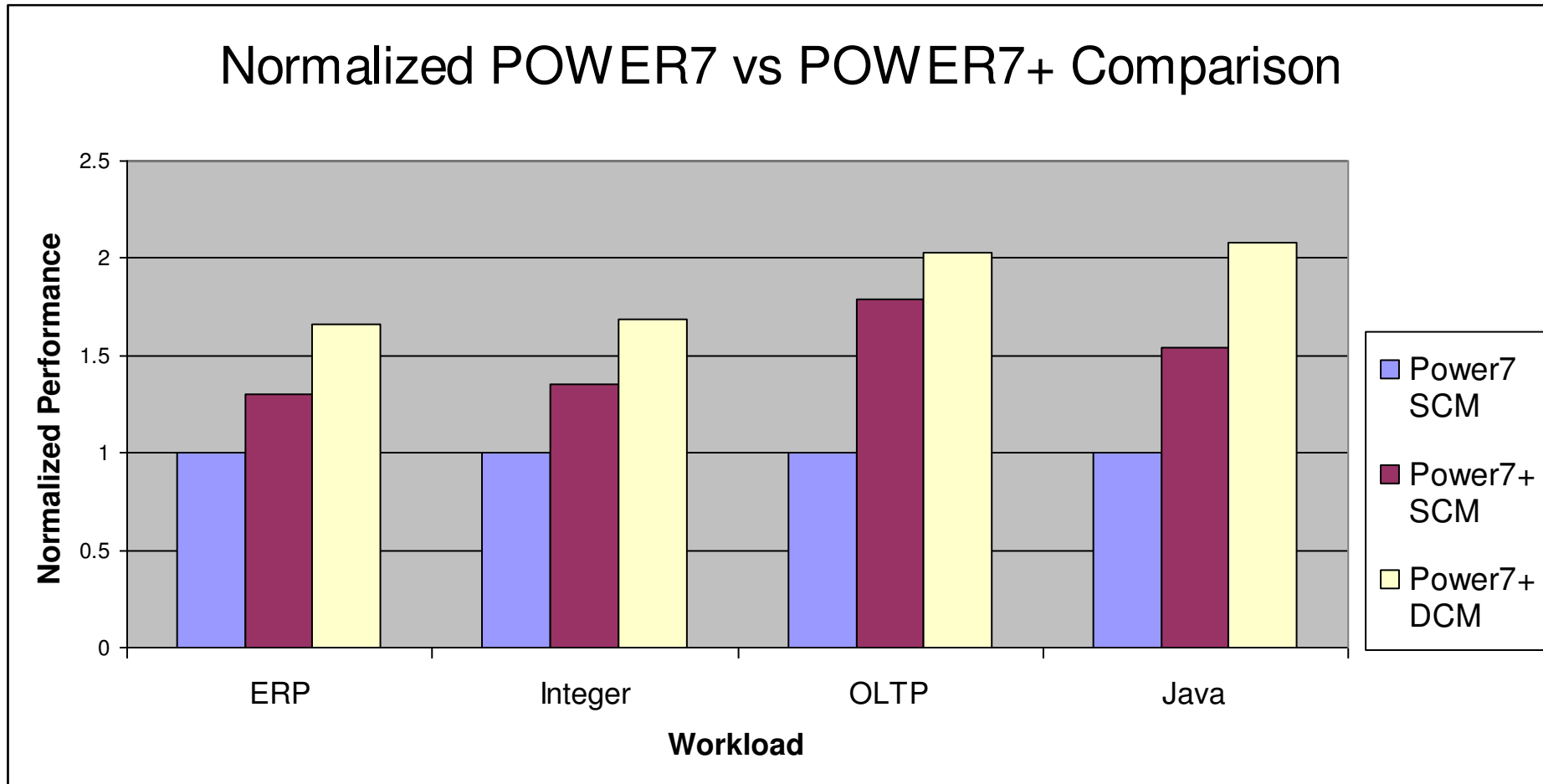
L3 Power-Gating 



# Optimized in Two Dimensions



# Performance View



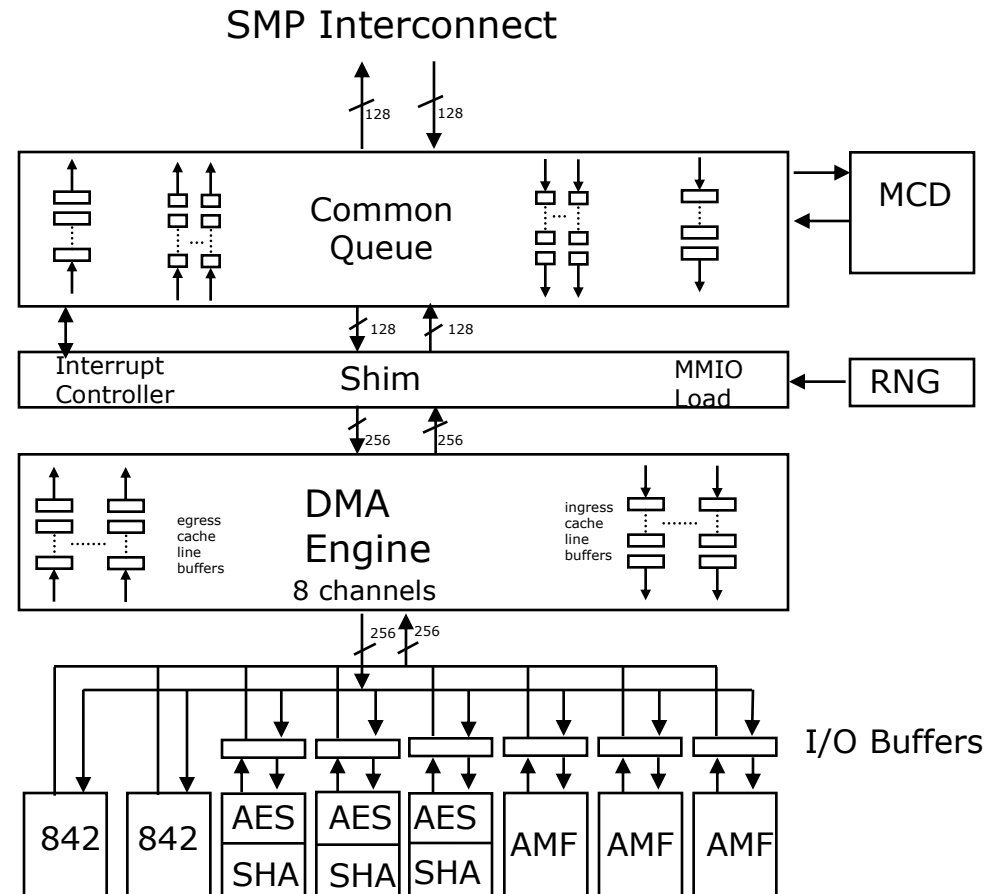
# POWER7+ Accelerators

- Provide CPU off-load and workload speedup for SSL, encrypted file system, and active memory expansion (AME).
  - Asymmetric Math Functions (AMF)
    - RSA cryptography
    - ECC (elliptic curve cryptography)
  - Advanced Encryption Standard (AES)/Secure Hash Algorithm (SHA)
    - Symmetric-key cryptography with combinational modes
  - Random Number Generator (RNG) – True hardware entropy generator
    - Cannot be algorithmically reverse engineered
  - 842 proprietary compression algorithm
    - High bandwidth, area efficient
  
- Integrated across silicon, ISA, hypervisor, and OS

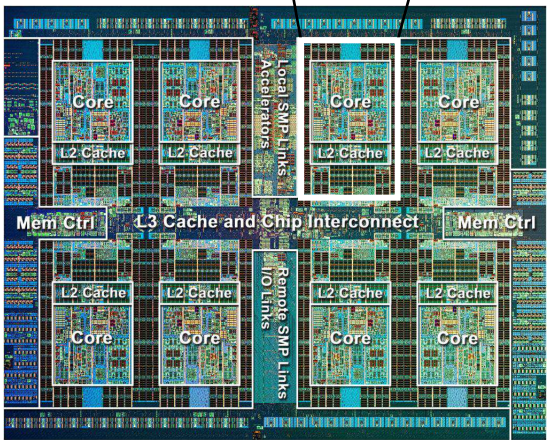
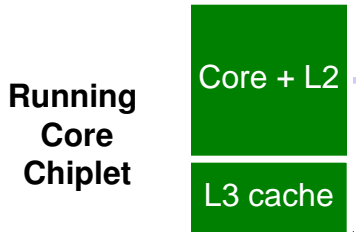


# Accelerators Details

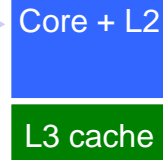
- **Advanced Encryption Standard engine**
  - Modes: ECB, CBC, CTR, CCM, CCA, GCM, GCA, GMAC, CM, F8, XBC-MAC-96
  - Key lengths: 128b, 192b, 256b
  - Three engines
- **Secure Hash Algorithm engine**
  - Modes: SHA-1, SHA-256, SHA-512, MD5
  - HMAC supported for SHA
  - Three engines
- **Asymmetric Math Functions**
  - Modular math functions for RSA (Rivest, Shamir, Adleman) and ECC (elliptic curve cryptography): mod add, mod subtract, mod inverse, mod reduction, mod multiplication, mod exponentiation, mod exponentiation CRT(integer only)
  - Point functions for ECC GF(p) and GF(2m): point add, point double, point multiply
  - RSA lengths: 512b, 1024b, 2048b, 4096b
  - ECC GF(p) lengths: 192b, 224b, 256b, 384b, 521b (SuiteB)
  - ECC GF(2m) lengths: 163b, 233b, 283b, 409b, 571b (SuiteB)
- **Random Number Generator**
  - All digital design which produces 64b random numbers accessible by MMIO load instructions
  - Correctness verified against the NIST Random Number Generator Test Suite
- **Active Memory Expansion**
  - IBM-proprietary algorithm with 8B-, 4B-, and 2B-phrase parsings
  - Throughput: Up to 8 bytes of compression or 8 bytes of decompression per bus cycle.
- **MCD**
  - Hardware to predict whether memory access is on-node or off-node.



# POWER7+ Sleep & Winkle Overview

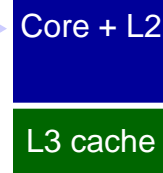


**Nap**  
(per core)



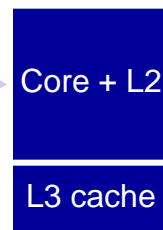
Stop clocks to only processor core execution engines.  
Leave all caches running.  
Saves ~ 10% power with ~ 5us Latency

**Sleep**  
(per core)



Power OFF the core plus private L2 cache.  
Requires restore/re-init to wakeup.  
Leave shared L3 cache running.  
Saves ~ 80% power with ~3ms Latency

**Winkle**  
(per chiplet)

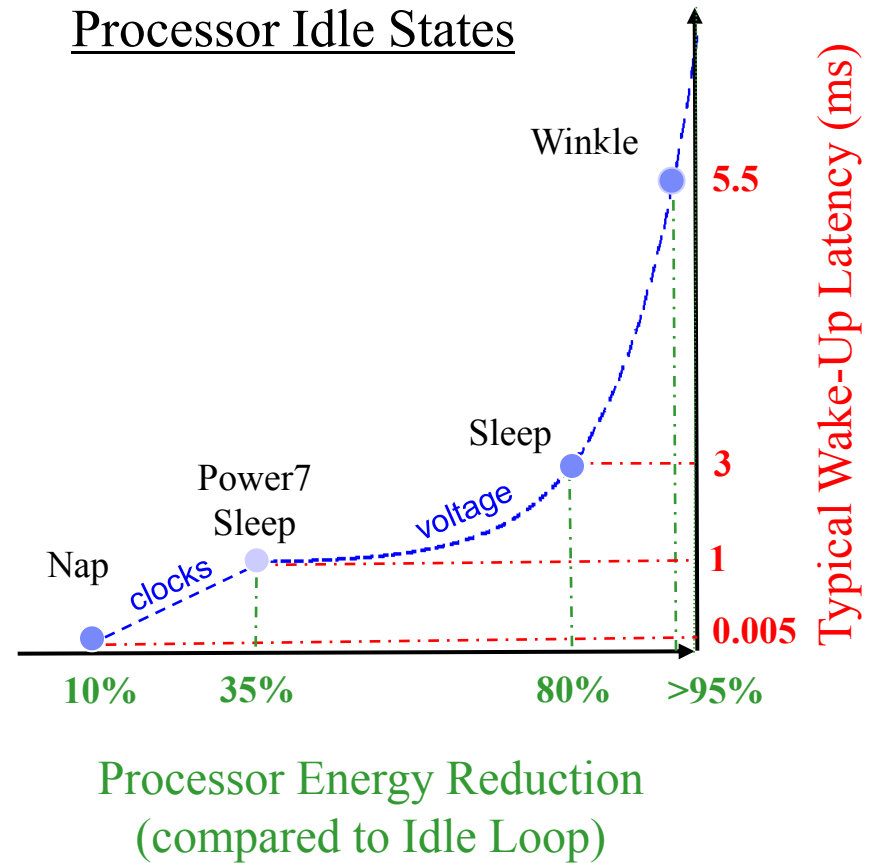


Power OFF the entire chiplet.  
Requires restore/re-init to wakeup.  
Takes offline 1/8 of the shared L3 cache.  
Saves > 95% power with < 6ms Latency

# Save Energy When Idle

Three idle states were implemented to optimize power vs. latency

- **Nap** (Continued POWER7 support)
  - Optimized for wake-up time
  - Turn off clocks to execution units only
  - Caches remain coherent
  
- **Sleep** (Improved from POWER7)
  - More savings at increased latency
  - Purge and power off core plus L2 caches
  - Leave shared L3 cache running
  
- **Winkle** (New for POWER7+)
  - Maximum savings at higher latency
  - Purge and power off entire chiplet
  - Takes eighth of chip L3 cache offline





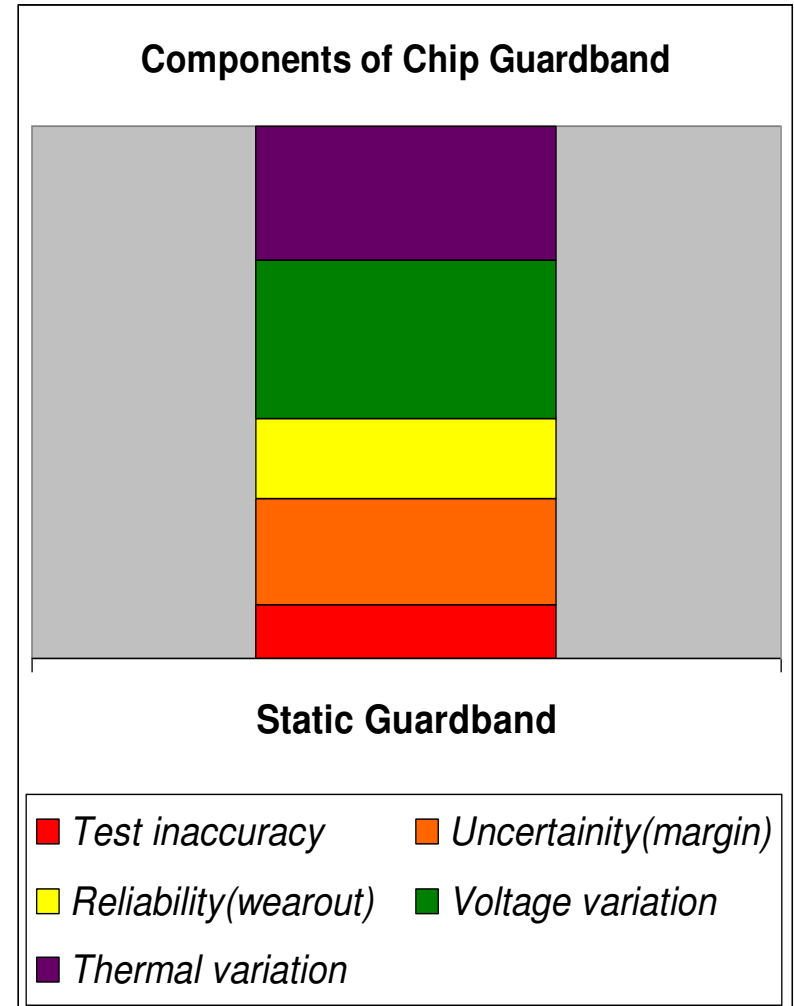
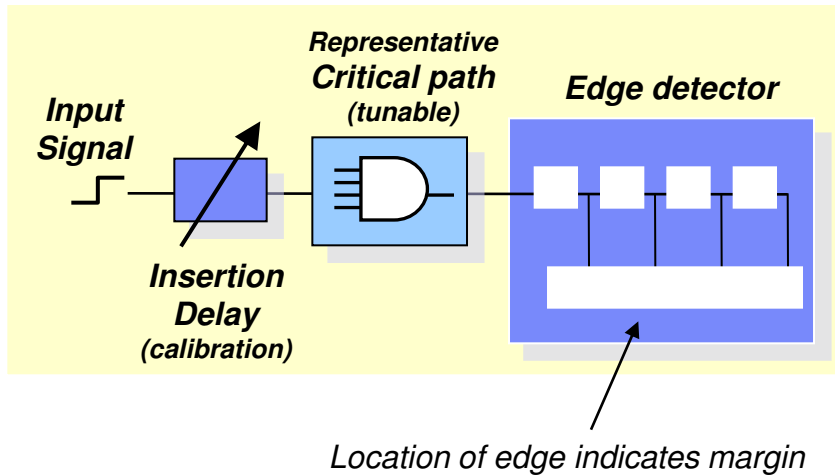
# Real Time Chip Guardband

## ➤ Conventional guardband

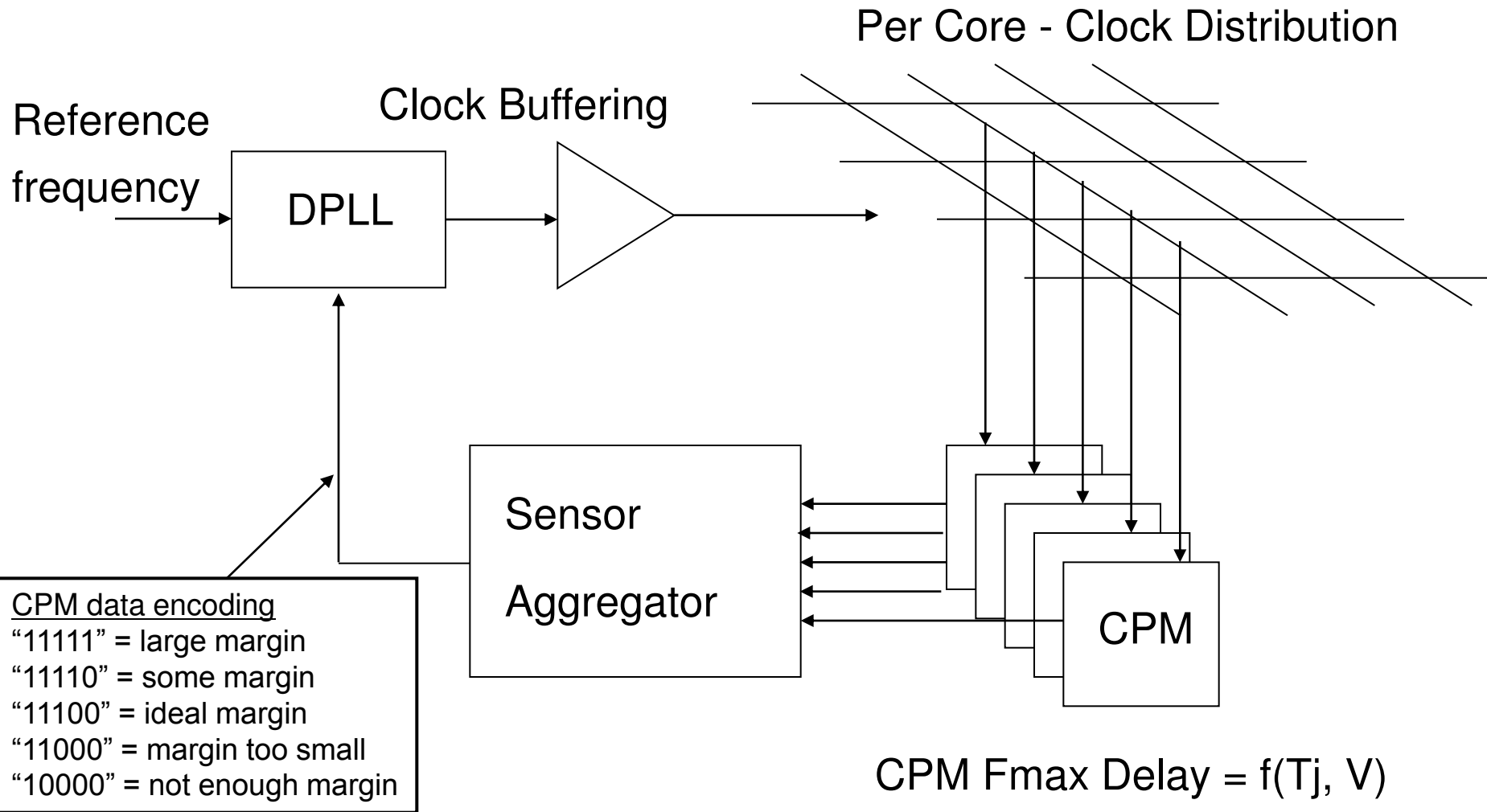
- Static, conservative voltage margins for potential worst-case conditions
- Causes unnecessary loss of energy efficiency during typical server usage

## ➤ Critical Path Monitor (CPM)

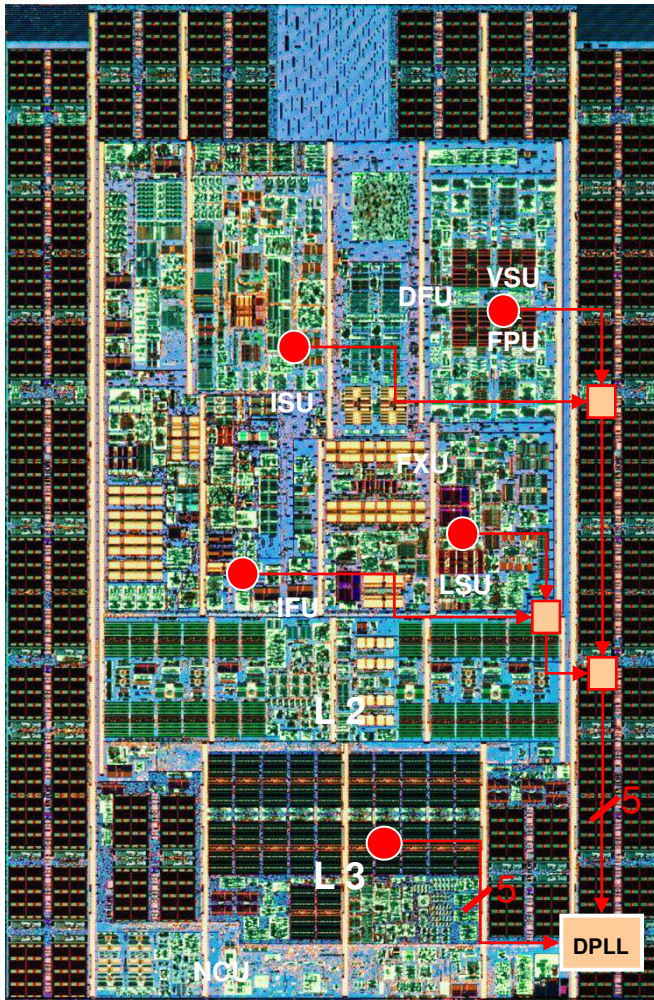
- Real Time detection of available circuit timing margin



# Real Time Guardband – DPLL/CPM feedback loop



# POWER7+ Core CPM Infrastructure

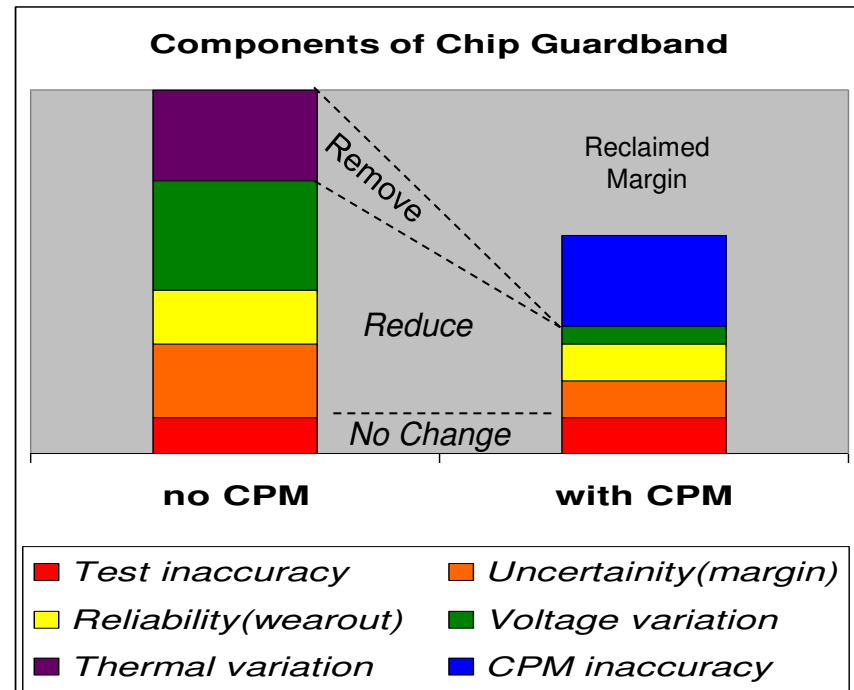


- = CPM (Critical Path Monitor)
- = AND Buffer

CPMs are strategically placed in known hot spots typically near micro-architecture critical paths.

The real time feedback from CPMs can reduce how much margin is needed for various guardband components.

Real-time guardbanding will allow for greater energy efficiency.

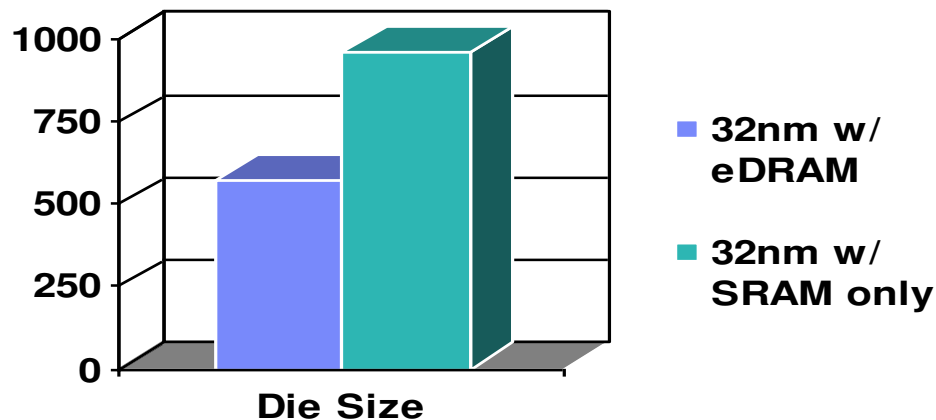




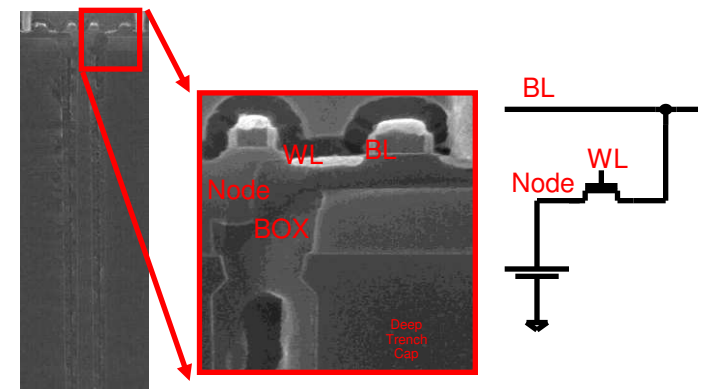
# Advanced 32nm Technology

- 32nm High-K Metal Gate (HKMG) SOI based logic technology
  - 3 logic transistor threshold voltages ( $V_t$ ) optimizes power/performance
  - 13-layer BEOL metal stack minimizes cross die latency
    - 1x, 2x, 4x, 8x, & ultra-thick metal layers
  - eDRAM provides 3-4x density advantage over SRAM
- Advanced features make the node effectively perform as one with sub-32nm features

### EDRAM Density Gain

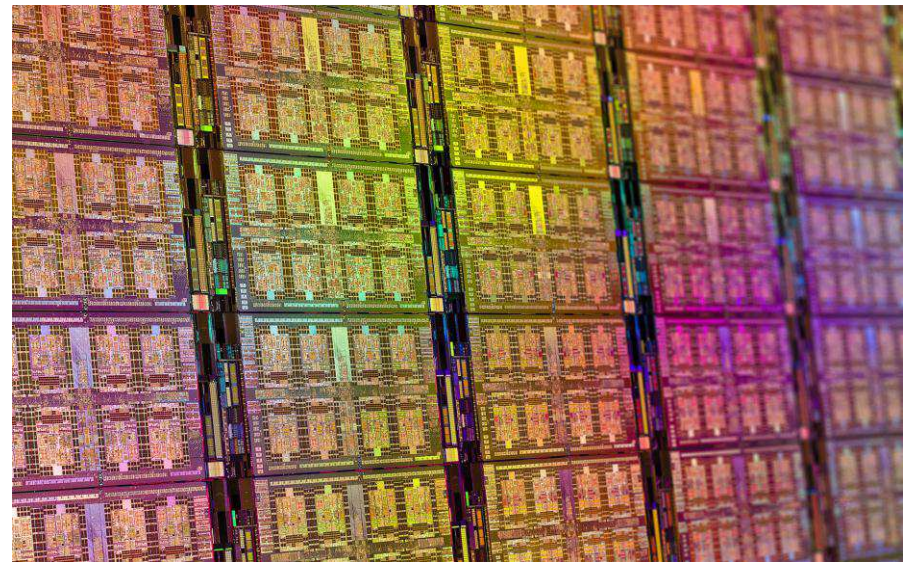
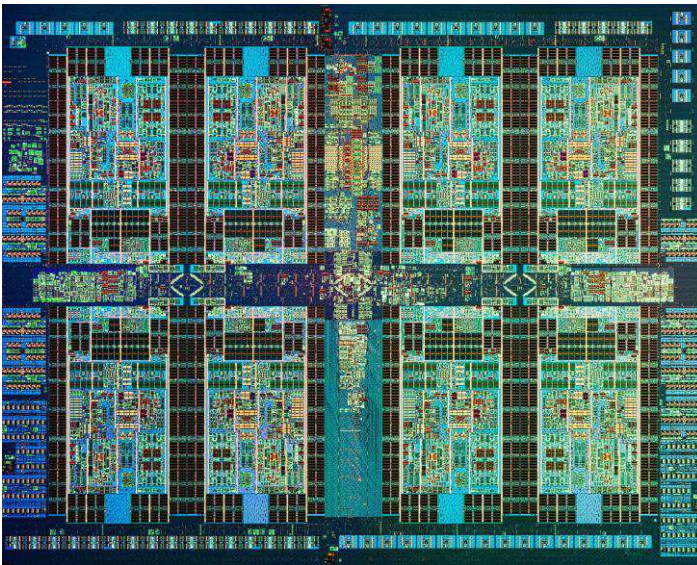


### EDRAM cell



# POWER7+: The next major step in IBM's roadmap

- Brings significant improvement to both scale up & scale out systems.
- The new accelerators optimize specific functions while offloading CPU.
- Advanced energy management greatly improves data center efficiency.



## Acknowledgements:

Many Thanks to the entire POWER7+ design, manufacturing and product teams.

Questions: Send email to: [sctaylor@us.ibm.com](mailto:sctaylor@us.ibm.com)